

Title (en)

Method of making metal composite materials

Title (de)

Verfahren zur Herstellung von metallischem Verbundmaterial

Title (fr)

Procédé de préparation d'un matériau composite métallique

Publication

EP 1043411 A3 20051102 (EN)

Application

EP 00105246 A 20000314

Priority

SE 9901206 A 19990406

Abstract (en)

[origin: EP1043411A2] The present invention provides a method of producing a metal composite material by dissolving at least one inorganic metal salt of Mo and/or W optionally together with one or more organic iron group metal salts in water and possibly at least another polar solvent, complex binding the metals with at least one complex former comprising functional groups in the form of OH or NR₃, (R=H or alkyl). The amount of said salt of Mo and/or W in the solution should be no more than $4 \times 10^{-3} \times$ (wt% H₂O)² g/100 ml solution and not less than 10 wt-% water. The method further includes adding hard constituent powder to the solution, evaporating the solvent and heat treating the remaining powder in an inert and/or reducing atmosphere. As a result coated hard constituent powder is obtained which after addition of pressing agent and optionally with other coated hard constituent powders and/or carbon to obtain the desired composition can be compacted and sintered according to standard practice.

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C22C 1/05

IPC 8 full level

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C-Set (source: EP US)

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[DPA] EP 0916743 A1 19990519 - SANDVIK AB [SE]

Cited by

EP2678514A4; DE102008052559A1; EP2436793A1; US10647614B2; US10766823B2

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